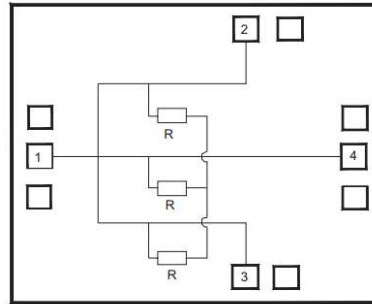


Performance

- Frequency: 8-12GHz
- Insertion loss: 0.7dB
- Chip size: 1.45*1.25*0.1mm

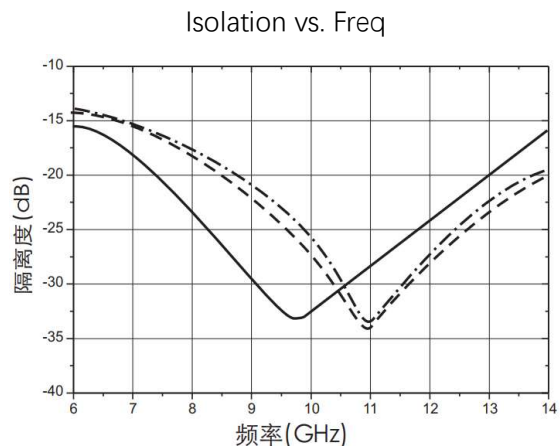
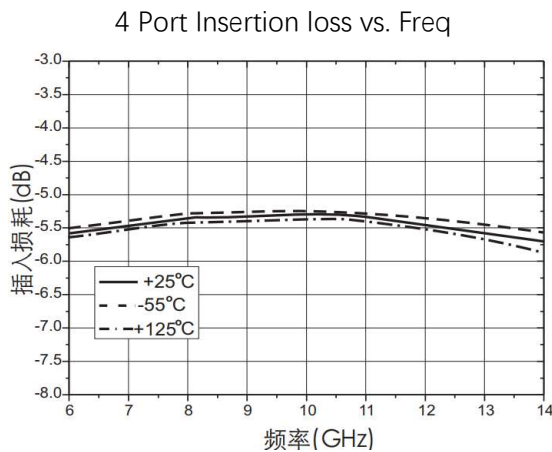
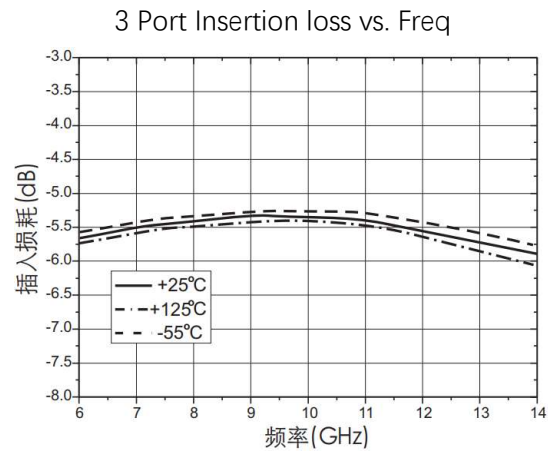
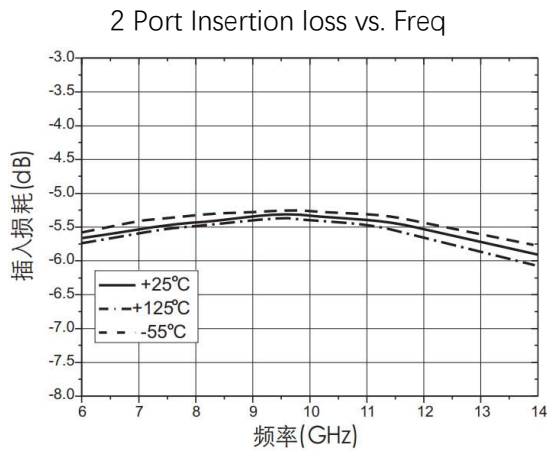
Function Diagram



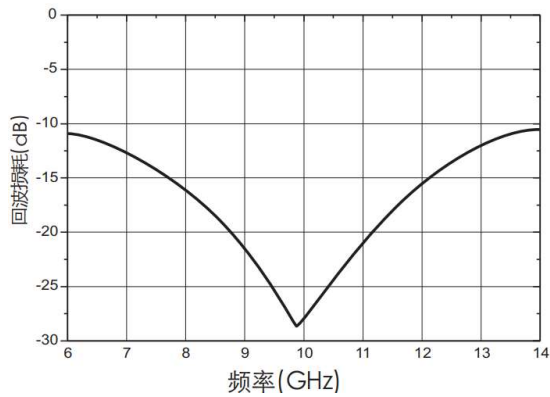
Electrical Specifications (Ta=+25°C, 50Ω system)

Parameter	Min	Typical	Max	Unit
Frequency Range		8~12		GHz
Insertion Loss	-	0.7	0.9	dB
Insertion Loss Ripple	-	±0.2	-	dB
Isolation	16	22	-	dB
Input Return Loss	15	20	-	dB
Output Return Loss	14	20	-	dB

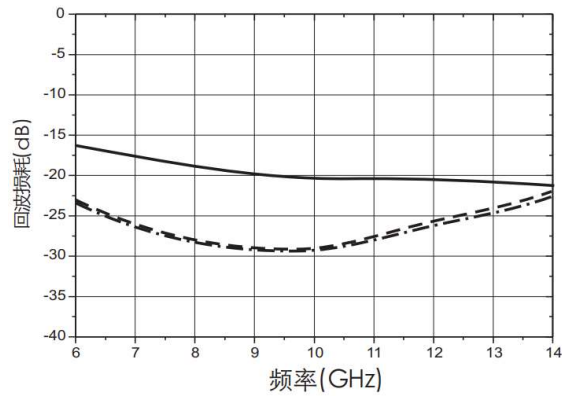
Test Curves



Input Return Loss vs. Freq



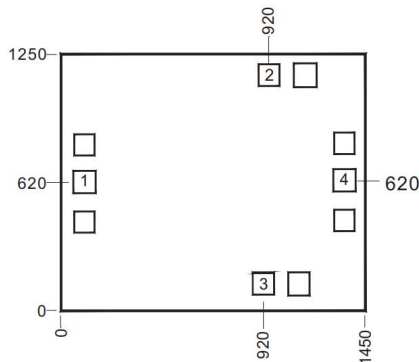
Output Return Loss vs. Freq



Absolute Max Ratings

Parameter	Value
Input Signal Power	+33dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Static protection Grade (HBM)	Class 1A

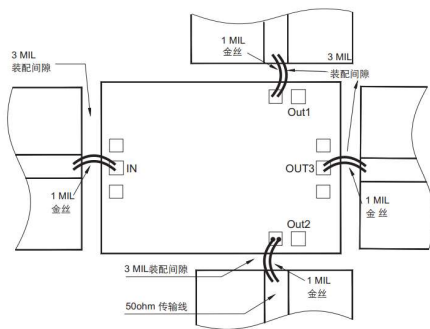
Outline Size



Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: $100 \times 100 \mu\text{m}$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50 \mu\text{m}$

Assembly Diagram



Bonding Definition

No.	Number	Description
1	IN	RF input, 50ohm
2,3,4	Out1,Out2,Out3	RF output, 50ohm
	GND	Bottom must be grounded